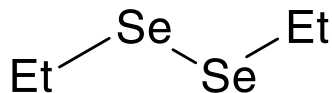


Catalog # 34-0380 Diethylselenide, min. 97%



## Thermal Behavior:

- Boiling point: 74-75°C/14 Torr [1]; 68-70 °C/9-10 Torr [2]
- Vapor pressure: 1.9 Torr/51 °C [4]

## Technical Notes:

1. ALD/CVD precursor for selenide thin film deposition.

Target Deposit	Deposition Technique	Delivery Temperature	Pressure	Co-reactants	Deposition Temperature	Ref.
TiSe <sub>x</sub>	CVD	70°C	AP	TiCl <sub>4</sub>	450-600°C	3
MeSe <sub>2</sub> M=Fe, Co, Ni	ALD	51°C	0.4 Torr	M(amd) <sub>2</sub> , <sup>P</sup> LH <sub>2</sub>	150-240°C (Fe) 150-210°C (Co) 120-180°C (Ni)	4

## References:

1. [Z. Anorg. Allg. Chem. 1960, 305, 88.](#)
2. [Inorg. Chim. Acta. 1981, 55, 171.](#)
3. [Chem. Vap. Deposition 2006, 12, 54.](#)
4. [Chem. Mater. 2021, 33, 2478.](#)